

## **PCIM Asia 2024 Round Table Meeting Agenda Power Source Technology of Low-altitude eVTOL**

### **Background:**

According to the **Research Report on China's Low-altitude Economic Development (2024)** released by China Center for Information Industry Development, CCID on April 1 shows that the scale of China's eVTOL industry has reached 980 million yuan in 2023, a year-on-year increase of 77.3%. And it is expected to reach 9.5 billion yuan by 2026. Under the background, the meeting will discuss how power semiconductor devices in the power electronics industry welcome this new market and help the development of eVTOL.

**Time:** Aug. 28, 13:30 – 16:00

**Venue:** Meeting Room 9D, Hall 11, Shenzhen World Exhibition Center

**Form:** A private and small round table with approximately 20 participants

**Topic:** Discussion on power source technology for low-altitude eVTOL

### **Agenda:**

13:30-14:00	Registration
14:00-14:10	Opening by chairperson
14:10-15:00	Industry development and policy for low-altitude eVTOL
	Technical background and trends for low-altitude eVTOL
15:00-15:50	Application of power semiconductor devices for low-altitude eVTOL
	Solutions for power source technology of low-altitude eVTOL
15:50-16:00	Summary, group photo and networking

## **PCIM Asia 2024 Round Table Meeting Agenda Product Technology and Application Scenarios of GaN**

### **Background:**

GaN power semiconductor products are widely used in various application scenarios, such as fast charging for intelligent devices, automotive, data centers and etc.. According to market research from Frost & Sullivan, a renowned consulting firm, the primary growth driver for GaN power semiconductors comes from fast chargers and adapters for electronic products. At present, the cost and technology of GaN remains key breakthrough.

**Time:** August 29, 10:00-12:30

**Venue:** Meeting Room 9D, 2<sup>nd</sup> Floor, Hall 11, Shenzhen World Exhibition Center

**Format:** A private and small round table with approximately 20 participants

**Topic:** Discussing GaN from multiple dimensions such as it's technology, cost, and application scenarios.

### **Agenda:**

10:00-10:30	Registration
10:30-10:40	Opening by chairperson
10:40-11:30	Characteristics and packaging challenges of GaN,
	Prospects of GaN technology
11:30- 12:20	Application scenarios of GaN (university research projects)
	Challenges of GaN high-reliability applications
12:20-12:30	Summary, group photo and networking